

**TIF™ 035AB-05S** is a highly thermal conductive, liquid gap filling material. It is provided with two-component and different temperature curing system. The product was supplied as highly thermal conductive, soft and elastomer, non-flow characteristic, easy for coupling on electrical devices modul. It can transmit to the metal housing or dissipation plate from the separate elements or even the entire PCB, which in effect enhances the efficiency and life-time of the heat-generating electronic components. It is liquid approach offer variety of thickness, replacing individual di-cut and specific pad thickness. Different from grease, the cured product is dry and easy clean. It can intended for use in multi-chips thermal applications.

**Features**

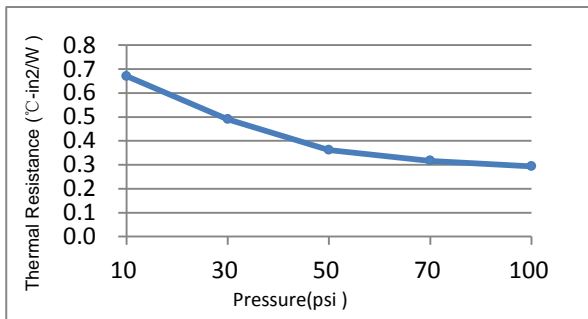
- 》 Good thermal conductivity: **3.5 W/mK**
- 》 Two-part formulation for easy storage
- 》 Excellent low and high temperature mechanical and chemical stability
- 》 Ultra-conforming low-stress interface application
- 》 Ambient or accelerated cure schedules
- 》 Optimized shear thinning characteristics for ease of dispensing

**Application**

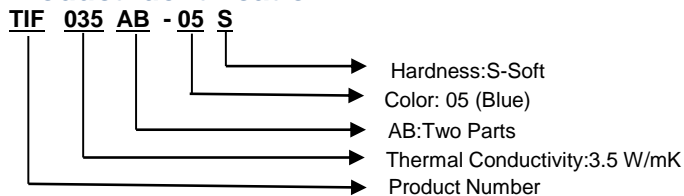
- 》 Computer and peripherals
- 》 Telecommunications
- 》 Automotive electronics
- 》 Thermally conductive vibration dampening
- 》 Heat sink and any heat generating semiconductor

Typical Properties of TIF™035AB-05S		
Typical Uncured Material		
PROPERTY	NUMERICAL	TEST METHOD
Color/Part A	White	Visual
Color/Part B	Blue	Visual
Viscosity as Mixed (cps)	20000cps	ASTM D2196
Density	3.1 g/cc	ASTM D792
Mix Ratio	1:1	*****
Shelf Life@25°C	6 months	*****
Cure Schedule		
Pot Life @ 25°C	60 min	*****
Cure @ 25°C	16~24 hours	*****
Cure @ 100°C	30 min	*****
Cure Properties		
Color	Blue	Visual
Hardness	55 Shore 00	ASTM D2240
Continuous Use Temp	-45 ~ 200°C	*****
Voltage Strength	200 V/mil	ASTM D149
Dielectric Constant @1MHz	4.4	ASTM D150
Volume Resistivity	> 10 <sup>12</sup> Ohm-cm	ASTM D257
Flame Rating	94 V0	E331100
Thermal Conductivity	3.5 W/mk	ISO22007-2
	3.5 W/mk	ASTM D5470

**Thermal impedance**



**Product Identification:**



Thermal Conductive Interface Materials Application Technology Download



<http://www.ziitek.com>

**Product Specification**

50 cc/pc, 48 pc/box; 400 cc/pc, 9 pc/box

We offer the custom packaged in syringes for automated dispensing applications. Please contact us for confirming.

Thermally Conductive Materials | Thermally Conductive Plastics | Heat Generating Materials | Shielding Materials | Foaming Silica Gel | Die-Cutting Products

**Canada:**  
Tel: +001-604-2998559  
E-mail: sales@thermazig.com

**China:**  
Tel: +86-769-38801208  
E-mail: frances@ziitek.com.tw

**Taiwan:**  
Tel: +886-2-22771007  
E-mail: frances@ziitek.com.tw

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.